

Data Sheet Issue:- 3

Phase Control Thyristor Types N4085Z#080 and N4085Z#120

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
Vdrm	Repetitive peak off-state voltage, (note 1)	800-1200	V
Vdsm	Non-repetitive peak off-state voltage, (note 1)	800-1200	V
V _{RRM}	Repetitive peak reverse voltage, (note 1)	800-1200	V
Vrsm	Non-repetitive peak reverse voltage, (note 1)	900-1300	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
Ιτ(Αν)Μ	Maximum average on-state current, T _{sink} =55°C, (note 2)	4085	А
I _{T(AV)M}	Maximum average on-state current. T _{sink} =85°C, (note 2)	2743	А
Ιτ(Αν)Μ	Maximum average on-state current. T _{sink} =85°C, (note 3)	1609	А
IT(RMS)M	Nominal RMS on-state current, T _{sink} =25°C, (note 2)	8161	А
I _{T(d.c.)}	D.C. on-state current, T _{sink} =25°C, (note 4)	6841	А
I _{TSM}	Peak non-repetitive surge t _p =10ms, V _{rm} =0.6V _{RRM} , (note 5)	64.0	kA
Ітѕм2	Peak non-repetitive surge t _p =10ms, V _{rm} ≤10V, (note 5)	70.0	kA
l²t	$I^{2}t$ capacity for fusing t_{p} =10ms, V_{rm} =0.6 V_{RRM} , (note 5)	20.5×10 ⁶	A ² s
l²t	$I^{2}t$ capacity for fusing t_{p} =10ms, V_{rm} ≤10V, (note 5)	24.5×10 ⁶	A ² s
(-1: (-14)	Critical rate of rise of on-state current (repetitive, 60s), (Note 6)	150	A/µs
(di/dt) _{cr}	Critical rate of rise of on-state current (non-repetitive), (Note 6)	300	A/µs
Vrgm	Peak reverse gate voltage	5	V
P _{G(AV)}	Mean forward gate power	5	W
Рсм	Peak forward gate power	30	W
T _{j op}	Operating temperature range	-40 to +125	°C
T _{stg}	Storage temperature range	-40 to +150	°C

Notes:-

- 1) De-rating factor of 0.13% per °C is applicable for T_j below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 125°C T_j initial.
- 6) $V_D=67\% V_{DRM}$, $I_{FG}=2A$, $t_r \le 0.5 \mu s$, $T_{case}=125^{\circ}C$.



Characteristics

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
Vтм	Maximum peak on-state voltage	-	-	1.06	I _{TM} =3000A	V
Vтм	Maximum peak on-state voltage	-	-	1.55	I _{TM} =12300A	V
Vτ	Threshold voltage	-	-	0.85		V
rs	Slope resistance	-	-	0.07		mΩ
(dv/dt) _{cr}	Critical rate of rise of off-state voltage	1000	-	-	V _D =80% V _{DRM} , linear ramp, gate o/c	V/µs
I _{DRM}	Peak off-state current	-	-	200	Rated V _{DRM}	mA
Irrm	Peak reverse current	-	-	200	Rated V _{RRM}	mA
Vgt	Gate trigger voltage	-	-	3.0	T 0500 N/ 401/ L 04	V
lgт	Gate trigger current	-	-	300	T _j =25°C V _D =10V, I _T =3A	mA
Vgd	Gate non-trigger voltage	-	-	0.25	Rated V _{DRM}	V
Iн	Holding current	-	-	1000	Tj=25°C	mA
t _{gd}	Gate-controlled turn-on delay time		0.5	1.0	VD=67% VDRM, IT=1000A, di/dt=10A/µs,	μs
t _{gt}	Turn-on time	-	1.5	2.0	I _{FG} =2A, t _r =0.5µs, T _j =25°C	μs
Qrr	Recovered charge	-	1850	-		μC
Qra	Recovered charge, 50% Chord	-	1000	1500	I _{TM} =1000A, t _p =1000μs, di/dt=10A/μs,	μC
Irr	Reverse recovery current	-	110	-	Vr=50V	А
trr	Reverse recovery time	-	18.0	-		μs
*	Turn-off time	-	80	-	I _{TM} =1000A, t _p =1000μs, di/dt=10A/μs, Vr=50V, Vdr=80%V _{DRM} , dVdr/dt=20V/μs	
tq		-	130	-	I _{TM} =1000A, t _p =1000µs, di/dt=10A/µs, V _r =50V, V _{dr} =80%V _{DRM} , dV _{dr} /dt=200V/µs	μs
R _{thJK}	Thermal resistance, junction to heatsink	-	-	0.011	Double side cooled	K/W
∙ `thJK		-	-	0.022	Single side cooled	K/W
F	Mounting force	27	-	47		kN
Wt	Weight	-	1.7	-		kg

Notes:-

1) Unless otherwise indicated $T_j=125^{\circ}C$.

2) For other clamp forces, please consult factory.

Notes on rupture rated packages. This product is available with a non-rupture rated package. For additional details on these products, please consult factory.



Notes on Ratings and Characteristics

1.0 Voltage Grade Table

Voltage Grade	Vdrm Vdsm Vrrm V	V _{RSM} V	V _D V _R DC V
08	800	900	560
12	1200	1300	810

2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T_j below 25°C.

4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

5.0 Snubber Components

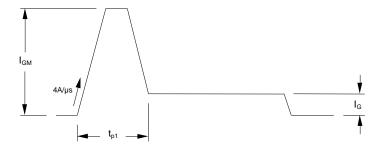
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 300A/µs at any time during turnon on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 150A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of I_{GM} should be between five and ten times I_{GT} , which is shown on page 2. Its duration (t_{p1}) should be 20µs or sufficient to allow the anode current to reach ten times I_L , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current I_G should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times I_{GT} .



8.0 Computer Modelling Parameters

8.1 Device Dissipation Calculations

$$I_{AV} = \frac{-V_0 + \sqrt{V_0^2 + 4 \cdot f f^2 \cdot r_S \cdot W_{AV}}}{2 \cdot f f^2 \cdot r_S} \quad \text{and:} \quad \begin{aligned} W_{AV} &= \frac{\Delta T}{R_{th}} \\ \Delta T &= T_{i\max} - T_{Hs} \end{aligned}$$

Where V_0=0.85V, $r_{s}{=}0.07m\Omega,$

 R_{th} = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

Supplementary Thermal Impedance							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave Double Side Cooled	0.0124	0.0122	0.0121	0.0119	0.0117	0.0113	0.011
Square wave Single Side Cooled	0.0249	0.0248	0.0247	0.0246	0.0244	0.0241	0.022
Sine wave Double Side Cooled	0.0168	0.0140	0.0131	0.0118	0.0112		
Sine wave Single Side Cooled	0.0249	0.0247	0.0246	0.0244	0.0241		

Form Factors							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.464	2.449	2	1.732	1.414	1.149	1
Square wave	3.98	2.778	2.22	1.879	1.57		

8.2 Calculating V_T using ABCD Coefficients

The on-state characteristic I_T vs. V_T , on page 6 is represented in two ways;

- (i) the well established V_0 and r_s tangent used for rating purposes and
- a set of constants A, B, C, D, forming the coefficients of the representative equation for V_T in terms of I_T given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for V_T agree with the true device characteristic over a current range, which is limited to that plotted.

25°C Coefficients		125°C Coefficients		
А	0.724445691	А	0.611648808	
В	0.033101532	В	0.017470315	
С	3.973700×10⁻⁵	С	2.412100×10 ⁻⁵	
D	1.66727×10 ⁻³	D	4.31084×10 ⁻³	



8.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}} \right)$$

Where p = 1 to *n*, *n* is the number of terms in the series and:

- t = Duration of heating pulse in seconds.
- $r_t =$ Thermal resistance at time t.

 r_p = Amplitude of p_{th} term.

 τ_p = Time Constant of r_{th} term.

The coefficients for this device are shown in the tables below:

	D.C. Double Side Cooled						
Term	erm 1 2 3						
rp	5.38976×10 ⁻³	3.997241×10 ⁻³	1.653457×10 ⁻³				
τρ	1.460889	0.3018047	6.533081×10 ⁻³				

	D.C. Single Side Cooled							
Term	erm 1 2 3 4 5							
r _p	0.01289943	2.475786×10 ⁻³	5.105832×10 ⁻³	7.74488×10 ⁻⁴	1.385198×10 ⁻³			
τρ	10.51046	5.571798	0.4648338	0.03866582	5.278089×10 ⁻³			

9.0 Reverse recovery ratings

(i) $Q_{ra}\xspace$ is based on 50% $I_{rm}\xspace$ chord as shown in Fig. 1

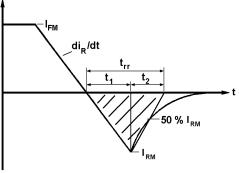


Fig. 1

(ii) Q_{rr} is based on a 150µs integration time i.e.

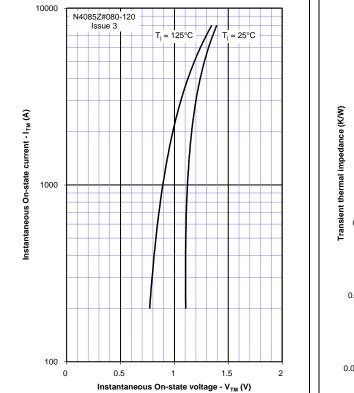
$$Q_{rr} = \int_{0}^{150\,\mu s} i_{rr}.dt$$

(iii)

$$K Factor = \frac{t_1}{t_2}$$



<u>Curves</u>







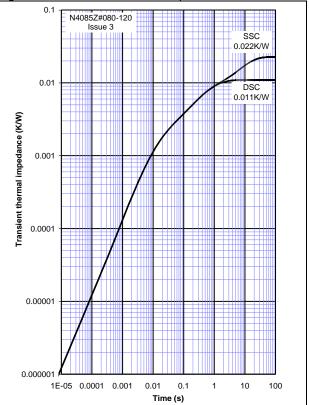
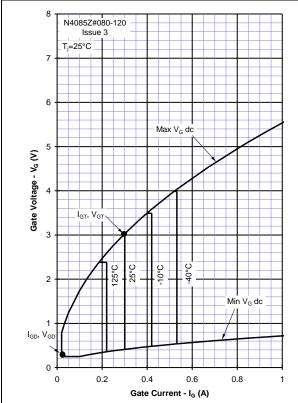


Figure 3 - Gate characteristics - Trigger limits





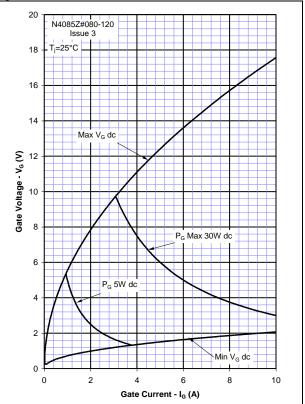
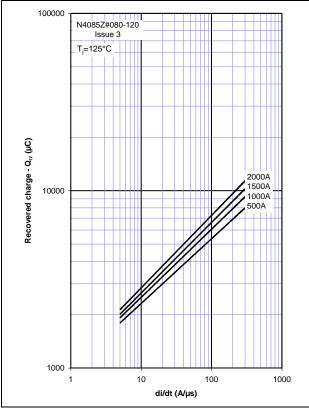
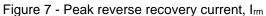
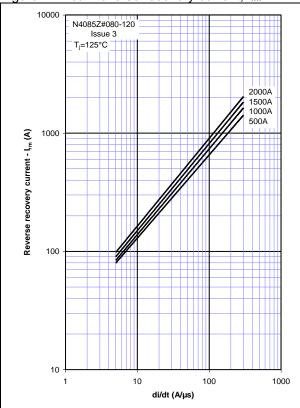


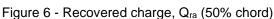


Figure 5 - Total recovered charge, Qrr









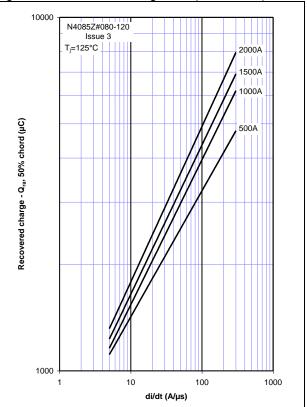


Figure 8 - Maximum recovery time, trr (50% chord)

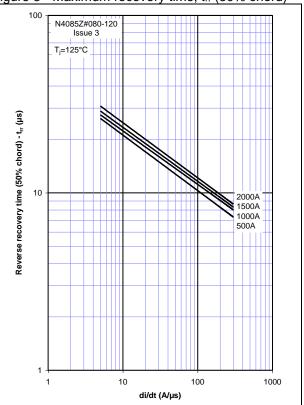




Figure 9 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

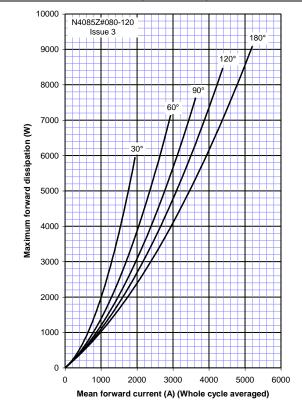


Figure 11 – On-state current vs. Power dissipation – Double Side Cooled (Square wave)

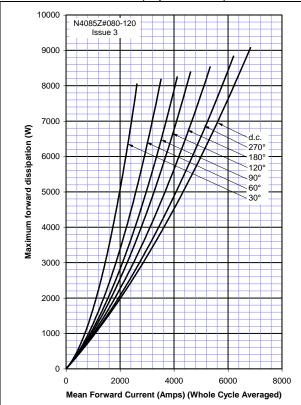


Figure 10 – On-state current vs. Heatsink temperature - Double Side Cooled (Sine wave)

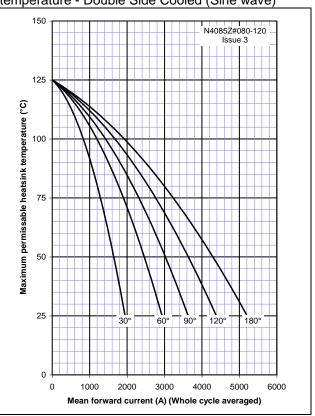
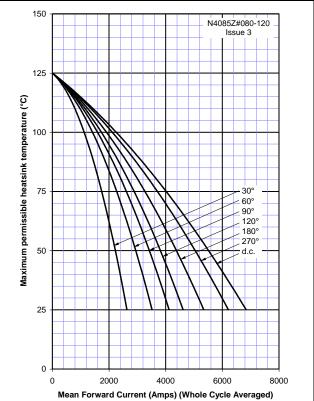


Figure 12 – On-state current vs. Heatsink temperature – Double Side Cooled (Square wave)





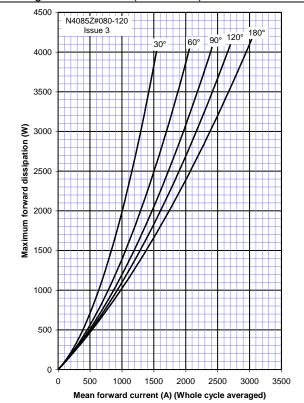


Figure 13 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)

Figure 15 – On-state current vs. Power dissipation – Single Side Cooled (Square wave)

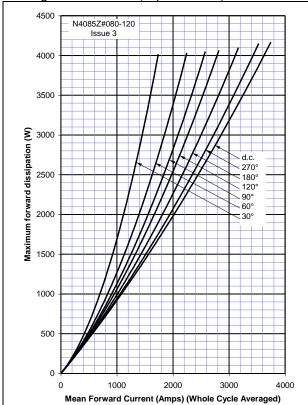


Figure 14 – On-state current vs. Heatsink temperature – Single Side Cooled (Sine wave)

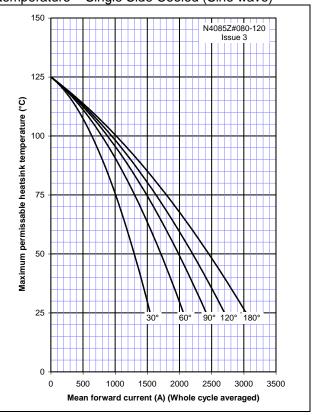
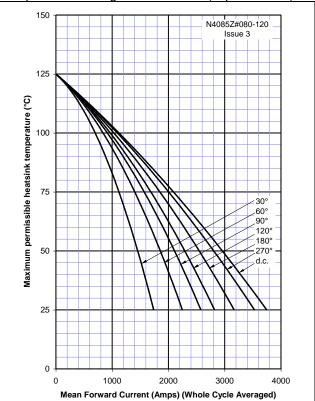
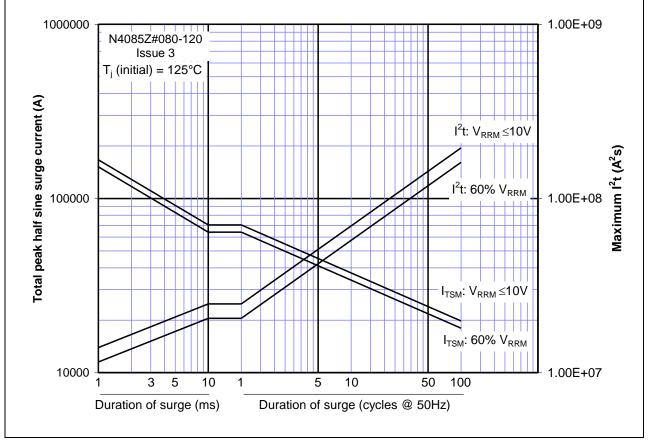


Figure 16 – On-state current vs. Heatsink temperature – Single Side Cooled (Square wave)



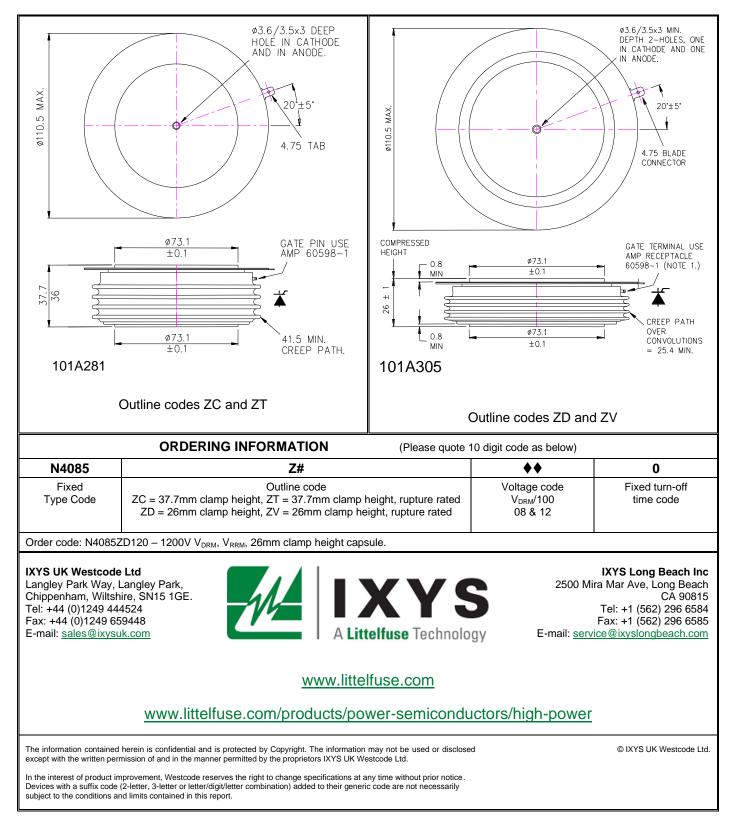








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